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HEET

U.S. DEPARTMENT  
OF COMMERCEPatent and  
Trademark Office10/17/01  
PTO  
09/977935Atty Docket #:  
ONS00323

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying part(ies):

Gordon M. Grivna

2. Title of invention:

SEMICONDUCTOR DEVICE AND METHOD OF  
INTEGRATING TRENCH STRUCTURES

10/17/01

3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

4. Name: Semiconductor Components Industries, LLC  
Patent Administration Dept. - MD A230  
P.O. Box 62890  
Phoenix, AZ 85082-2890

Execution date(s)  
of conveyance in  
order of inventor:

October 11, 2001

Additional name(s) &amp; address(es) attached?

☐ Yes☒ No

5. Application number(s) or patent number(s).

If this document is being filed together with a new application, execution date(s) of the  
application in order of inventor is:

October 11, 2001

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached?

☐ Yes☒ No6. Name and address of party to whom correspondence  
concerning document should be mailed:Name: ON SemiconductorInternal Address: Patent Administration Dept -  
MD A230Street Address: P.O. Box 62890City, State, Zip: Phoenix, AZ 85082-28906. Total number of applications and patents involved: 18. Total fee (37 C.F.R. §3.41) ..... \$ 40.00☐ Enclosed☒ Authorized to be charged to deposit account9. Deposit account number: 501086

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10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the  
original document.

James J. Stipanuk

44,358

Name of Person Signing

Reg. No.

Signature

Date

Total number of pages including cover sheet, attachments, and document: 2

OMB No. 0651-0011 (exp. 4/94)

10/25/2001 BT0N11 00000098 501086 09977935

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# ASSIGNMENT AND AGREEMENT


For good and valuable consideration, the receipt of which is hereby acknowledged, I, Gordon M. Grivna of Mesa, AZ, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a Limited Liability Company of the State of Delaware, doing business as ON Semiconductor, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States of America in and to certain inventions, entitled SEMICONDUCTOR DEVICE AND METHOD OF INTEGRATING TRENCH STRUCTURES, Attorney Docket No. ONS00323, described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by me, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any continuation, continuation-in-part, division, reissue, reexamination, extension, renewal, or substitute thereof.

I hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and I further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, continuation, continuation-in-part, division, reissue, reexamination, extension, renewal, or substitute, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

I agree that, when requested, I will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.


I covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for Gordon M. Grivna

STATE OF ARIZONA )  
COUNTY OF MARICOPA )

I, Linda Lee, a Notary Public in and for the County and State aforesaid, do hereby certify that Gordon M. Grivna, whose name is subscribed to the foregoing instrument, appeared before me this day in person and acknowledged that he/she signed, sealed and delivered the instrument as his/her free and voluntary act and deed for the uses and purposes therein set forth.

Given under my hand and notarial seal this 11th day of October, 2001.

  
\_\_\_\_\_  
Signature of Notary

